GBU8A THRU GBU8M

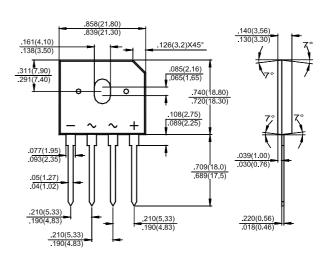
GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIERS Reverse Voltage – 50 to 1000 Volts Forward Current – 8.0 Amperes

Features

- · Glass passivated chip junction
- Reliable low cost construction utilizing molded
 plastic technique
- Ideal for printed circuit board
- Low forward voltage drop
- Low reverse leakage current
- High surge current capability

Mechanical Data

- Case: Molded plastic, GBU
- **Epoxy:** UL 94V-0 rate flame retardant
- Terminals: leads solderable per MIL-STD-202, Method 208 guaranteed
- Mounting Position: Any



GBU

Dimensions in inches and (millimeters)

Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	GBU8A	GBU8B	GBU8D	GBU8G	GBU8J	GBU8K	GBU8M	Units
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T_{C} = 100 $^{\circ}C$ $^{1)}$	I _{F(AV)}	8							А
Peak forward surge current , 8.3 ms single half-sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	200						A	
Maximum forward voltage at 8A DC and 25 °C	VF	1							V
Maximum reverse current at $T_A = 25 \text{ °C}$ at rated DC blocking voltage $T_A = 125 \text{ °C}$	I _R	5 500							μA
Typical junction capacitance ³⁾	CJ	255 12			125		pF		
Typical thermal resistance 4)	R _{0JA}	21						°C/W	
Typical thermal resistance 4)	R _{θJC}	2.2							0/11
Operating and storage temperature range	T _J , T _S	-55 to +150							°C

 $^{\rm 1)}$ Units case mounted on 3.2 X 3.2 X 0.12" thick (8.2 X 8.2 X 0.3 cm) AI plate heatsink.

²⁾ Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with #6 screws.

³⁾ Measured at 1 MHz and applied reverse voltage of 4 VDC.

⁴⁾ Units mounted in free air, no heatsink on P.C.B., 0.5 X 0.5" (12 X 12 mm) copper pads, 0.375" lead length.



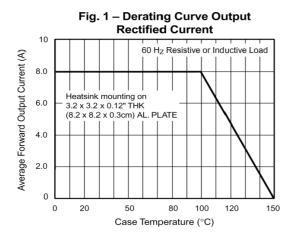


(Subsidiary of Semtech International Holdings Limited, a company listed on the Hong Kong Stock Exchange, Stock Code: 724)

SEMTECH ELECTRONICS LTD.

Dated : 06/02/2006 H

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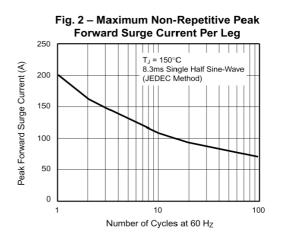


Fig. 3 – Typical Forward **Characteristics Per Leg** 100 Instantaneous Forward Current (A) 10 1 0.1 Pulse Width = 300µs 1% Duty Cycle T_J = 25°C 0.01 1.2 0.6 0.8 1.0 1.4 0.4 1.6 Instantaneous Forward Voltage (V)

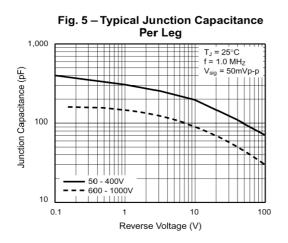
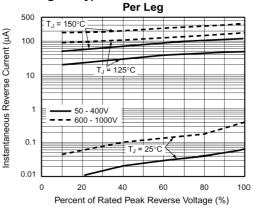
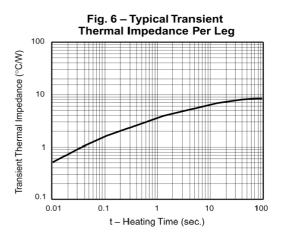


Fig. 4 – Typical Reverse Characteristics







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